

5/27/05

07-07-2005



102944657

To the Honorable Commissioner of Patents and

document or copy thereof.

1. Name of conveying party(ies): Date
Optonics, Inc. October 27, 2004
Additional name(s) of conveying party(ies) attached? Yes No

2. Name of receiving party(ies):
Name: Credence Systems Corporation
Internal Address:
Street Address: 1421 California Circle, 95035
City: Milpitas State: CA Zip: 95035
Additional name(s) & address(es) attached? Yes No

3. Nature of conveyance:
 Assignment Merger
 Security Agreement Change of Name
 Other RE-RECORD TO Execution Date: 10/27/04

CORRECT ASSIGNEE ON R/F 015962/0383

4. Application number(s) or registration number(s):
If this document is being filed together with a new application, the execution date of the application is: (Date of Filing)
A. Patent Application No.(s)
B. Patent No. 6,797,581
Additional numbers attached? Yes No

OPR/FINANCE
MAY 27 11 7 2005

5. Name and address of party to whom correspondence concerning document should be mailed:
Name: Joseph Bach
Internal Address: JBPatents.com
Street Address: 17460 Lakeview Drive
City: Morgan Hill State: CA Zip: 95037

6. Total number of applications and patents involved: 1
7. Total fee (37 C.F.R. 3.41)----- \$ 40.00
 Enclosed
 Authorized to be charged to deposit account
8. Deposit account number:

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9. Statement and signature.
To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

JOSEPH BACH Reg No. 37,771
Name of Person Signing

May 24, 2005
Date

Total number of pages including cover sheet, attachments and document: 4

Mail documents to be recorded with required cover sheet information to:
Commissioner of Patents & Trademarks, Box Assignments
Washington, D.C. 20231

06/02/2005 ECDOPER 00000004 6797581

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11-12-2004



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FORM PTO-1596 (Rev. 6-93) U.S. Patent and Trademark Office

U.S. Department of Commerce Patent and Trademark Office

To the Honorable Commissioner of Patents and Trademarks: Please record the attached original document or copy thereof.

1. Name of conveying party(ies): Optonics, Inc. Date: October 27, 2004. Additional name(s) of conveying party(ies) attached? No. 3. Nature of conveyance: X Assignment, Merger, Security Agreement, Change of Name, Other, Execution Date.

2. Name and address of receiving party(ies): Name: Credence, Inc. Internal Address: Street Address: 1421 California Circle, 95035. City: Milpitas State: CA Zip: 95035. Additional name(s) & address(es) attached? No.

4. Application number(s) or registration number(s): If this document is being filed together with a new application, the execution date of the application is: (Date of Filing) A. Patent Application No.(s) B. Patent No. 6,797,581 Additional numbers attached? No.

5. Name and address of party to whom correspondence concerning document should be mailed: Name: Joseph Bach Internal Address: JBPatents.com Street Address: 17460 Lakeview Drive City: Morgan Hill State: CA Zip: 95037

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9. Statement and signature. To the best of my knowledge and belief, the foregoing information is true and correct and any attached copy is a true copy of the original document.

JOSEPH BACH Reg No. 37,771 Name of Person Signing

Signature

November 1, 2004 Date

Total number of pages including cover sheet, attachments and document: 4

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11/10/2004 MSETACHE 00000034 6797581 01 FC:8021 40.00 DP

ASSIGNMENT OF PATENTS AND PATENT APPLICATIONS

WHEREAS, Optonics, Inc., hereinafter called "ASSIGNOR", a California corporation having its principal place of business at 2593 Coast Avenue, Suite 100, Mountain View, California 94043, is the assignee of certain patents and patent applications listed in Appendix A attached herewith and comprising two pages.

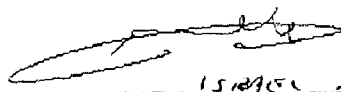
AND WHEREAS Credence Systems Corporation, a Delaware corporation, having it's principal place of business at 1421 California Circle Milpitas, California 95035, together with any successors, legal representatives or assigns thereof, called "ASSIGNEE" wants to acquire the entire right, title and interest in and to said patents and patent applications.

NOW, THEREFORE, in consideration of the sum of \$1.00, the receipt thereof is hereby acknowledged, and other good and valuable consideration, the receipt of which is hereby acknowledged, ASSIGNOR have sold, assigned, transferred and set over, and do hereby sell, assign, transfer and set over to ASSIGNEE the entire right, title and interest in and to said improvements, and said application and all divisions and continuations thereof, and all United States Letters Patents which may be granted thereon and all reissues, reexaminations and extensions thereof, and all priority rights under all available International Agreements, Treaties and Conventions for the protection of Intellectual property in its various forms in every participating country, and all applications for patents (including related rights such as utility-model registrations, inventor's certificates, and the like) heretofore or hereafter filed for said improvements in any foreign countries, and all patents (including all continuations, divisions, extensions, renewals, substitutes, and reissues thereof) granted for said improvements in any foreign countries; and we hereby authorize and request the United States Commissioner of Patents and Trademarks, and any officials of foreign countries whose duty it is to issue patents on applications as aforesaid, to issue all patents for said improvements to ASSIGNEE in accordance with the terms of this Assignment.

AND ASSIGNOR HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

IN TESTIMONY WHEREOF, I hereunto set my hand this 27 day of October, 2004

Signature of ASSIGNOR:


ISRAEL NIV

For Optonics Inc.

By: Israel Niv

Title: President and CEO

STATE OF CALIFORNIA

Application No.	Country	Title	Patent No.
09/995,548	United States	Time Resolved Non-Invasive Diagnostics System	6,621,275
10/457,988	United States	Time Resolved Non-Invasive Diagnostics System	
PCT/US01/38431	Patent Cooperation Treaty	Time Resolved Non-Invasive Diagnostics System	
2797156.3	European Patent Convention	Time Resolved Non-Invasive Diagnostics System	
2003-547980	Japan	Time Resolved Non-Invasive Diagnostics System	
2004-7007251	South Korea	Time Resolved Non-Invasive Diagnostics System	
91134678	Taiwan	Time Resolved Non-Invasive Diagnostics System	
10/052,011	United States	Bi-Concave Solid Immersion Lens	6,594,086
10/440,866	United States	Bi-Concave Solid Immersion Lens	6,778,327
10/883,542	United States	Bi-Concave Solid Immersion Lens	
PCT/US02/38538	Patent Cooperation Treaty	Bi-Concave Solid Immersion Lens	
2004-7007230	South Korea	Bi-Concave Solid Immersion Lens	
2822785.9	China P.R.	Bi-Concave Solid Immersion Lens	
91137365	Taiwan	Bi-Concave Solid Immersion Lens	
10/379,950	United States	Universal Platform for Integrated Circuit Analysis	
10/255,345	United States	Solid Immersion Lens Landing System	
10/930,454	United States	Solid Immersion Lens Landing System	
10/294,434	United States	Avalanche Photo Diode for Photon Counting Applications	6,720,588
10/721,915	United States	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	6,797,581
91133774	Taiwan	Avalanche Photo Diode for Photon Counting Applications	201324
PCT/US02/37366	Patent Cooperation Treaty	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	
2804016	European Patent Convention	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	
2003-648119	Japan	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	
91133774	Taiwan	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	
2820685.1	China P.R.	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	
2004-7007361	South Korea	Avalanche Photo Diode for Photon Counting Applications and Method Thereof	
10/222,107	United States	Spray Cooling Thermal Management System and Method for Semiconductor Probing, Diagnostics, and Failure Analysis	
60/385,524	United States	Inter & Intra Chip Signal Communication System for IC Devices and Method Using Hot Electron Photoemission	
10/379,925	United States	Spray Cooling and Transparent Cooling Plate Thermal Management System	
PCT/US03/036547	Patent Cooperation Treaty	Spray Cooling and Transparent Cooling Plate Thermal Management System	

APPENDIX A	Country	Title	Patent No.	2 of 2
Application No. 92132629	Taiwan	Spray Cooling and Transparent Cooling Plate Thermal Management System		
10/613,593	United States	Time Resolved Emission Spectra Analysis System		
10/408,988	United States	System and Method for Calibration of Testing Equipment using Device Photoemission		
PGT/US04/010728	Patent Cooperation Treaty	System and Method for Calibration of Testing Equipment using Device Photoemission		
93109727	Taiwan	System and Method for Calibration of Testing Equipment using Device Photoemission		
10/719,880	United States	Shutter Blade Position Detection		
10/645,013	United States	Beacon Circuit for Photo Emission Voltage Analysis		
10/872,595	United States	Integrated APD and Lens Assembly		
10/912,896	United States	Light Beam Apparatus and Method for Orthogonal Alignment of Specimen		
10/229,181	United States	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
92101517	Taiwan	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
03713326.1-1236	European Patent Convention	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
03802724.0	China P.R.	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
2063-566568	Japan	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
2004-7011746	South Korea	Apparatus and Method for Dynamic Diagnostic Testing of Integrated Circuits		
10/341,721	United States	Apparatus and Method for Measuring Characteristics of Dynamic Electrical Signals in Integrated Circuits		